

DDR3 DIMM, DDR3 SO DIMM

TE Internal #: 4-1932000-7

DDR3 DIMM, DIMM Sockets, Double Data Rate (DDR) 3, Board-to-

Board, 240 Position, Through Hole - Solder, Vertical Module

Orientation

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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR3 DIMM SOCKETS



DRAM Type: Double Data Rate (DDR) 3

Connector System: Board-to-Board

Number of Positions: 240

PCB Mounting Style: Through Hole - Solder

Module Orientation: Vertical

All DDR3 DIMM SOCKETS (13)

Features

Product Type Features

DRAM Type	Double Data Rate (DDR) 3
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket
Configuration Features	
Number of Positions	240
Module Orientation	Vertical
Body Features	
Ejector Type	Standard
Contact Features	
Contact Current Rating (Max)	.75 A
Mechanical Attachment	
Polarization	Left
PCB Mount Retention Type	Boardlock

Through Hole - Solder

PCB Mounting Style



Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	1 mm[.039 in]
Dimensions	
Row-to-Row Spacing	1.9 mm[.075 in]
Usage Conditions	
Operating Temperature Range	-55 – 155 °C[-67 – 311 °F]
Operation/Application	
Circuit Application	Signal
Packaging Features	
Packaging Method	Box & Tray, Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 260°C

Product Compliance Disclaimer

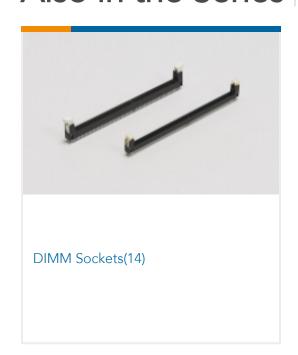
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach



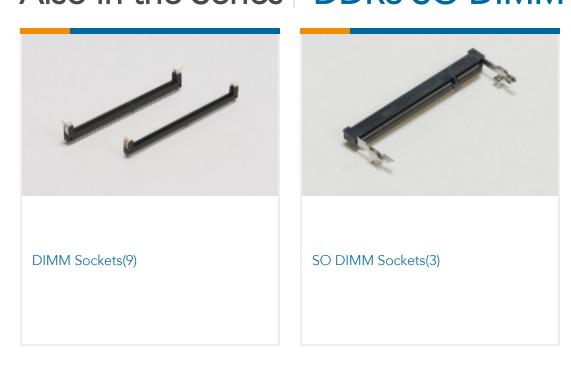
Compatible Parts



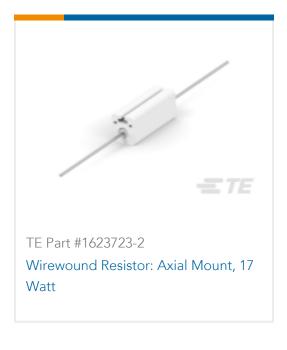
Also in the Series | DDR3 DIMM



Also in the Series | DDR3 SO DIMM



Customers Also Bought





















Documents

Product Drawings

VERTICAL DDR3 DIMM, 240 POSITION

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_4-1932000-7_F.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_4-1932000-7_F.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_4-1932000-7_F.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

6-1773457-3_DDR3_DIMM_SOCKETS

Product Specifications

Product Specification

English